

Product / Process Change Notification



N° 2019-109-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Change of wafer production and wafer test location from Infineon Technologies Austria AG, Villach, Austria to Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia and change of wafer diameter from 150 mm to 200 mm for TLE4263-2ES

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **7th October 2019**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JEESD46**“, which stipulates:
“**Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG
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Chairman of the Supervisory Board: Dr. Wolfgang Eder
Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Dr. Sven Schneider
Registered Office: Neubiberg
Commercial Register: München HRB 126492

Product / Process Change Notification



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► **Products affected:** Please refer to attached affected product list 1_cip19109_A

► **Detailed Change Information:**

Subject: Change of wafer production and wafer test location from Infineon Technologies Austria AG, Villach, Austria to Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia and change of wafer diameter from 150 mm to 200 mm for TLE4263-2ES

Reason: Due to continuously raising demand for Infineon automotive products exceeding the capacity in wafer fab Villach we have to transfer wafer fab and test location to the well-known FE location Kulim.
The 8 inch wafer manufacturing technology is the state of the art technology at INFINEON. Therefore the above mentioned products will be changed from 6 inch to 8 inch.

Description:	<u>Old</u>	<u>New</u>
wafer production location and wafer test location	■ Infineon Technologies Austria AG, Villach, Austria	■ Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia
wafer diameter	■ 6 inch	■ 8 inch

► **Product Identification:** Wafer lot numbers from Villach start with VCxxxxxx.
Wafer lot numbers from Kulim start with 1Exxxxxx.
Traceability assured via date code.
No change in SP ordering number.

► **Impact of Change:** Based on the qualification performed, Infineon does not see any negative impact on quality, function and reliability. No change in fit, form and function.
DeQuMa-IDs: SEM-PW-02 / SEM-PW-13 / SEM-TF-01

► **Attachments:** Affected product list 1_cip19109_A

► **Time Schedule:**

- Final qualification report: available
- First samples available: on request
- Intended start of delivery: 28-February-2020 or earlier after customer approval

If you have any questions, please do not hesitate to contact your local Sales office.

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Sales name	SP number	OPN	Package
TLE4263-2ES	SP000366102	TLE42632ESXUMA1	PG-DSO-8